ON Semiconductor

10/15/2019

Base Part	FQB34N20		
Orderable Part	FQB34N20TM-AM002	Total weight (mg)	1485.898

Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	12.3	Silicon (Si)	7440-21-3	100
Die Attach Solder		Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
	7.33	Tin (Sn)	7440-31-5	5
Lead Frame		Tin (Sn)	7440-31-5	0.6375
		Nickel (Ni)	7440-02-0	0.2541
	865.838	Copper (Cu)	7440-50-8	99.1084
Mold Compound-Black		2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	1.99731454
		Ortho Cresol Novolac Resin	29690-82-2	27.52601544
		Antimony Trioxide (Sb2O3)	1309-64-4	3.00436388
		Carbon Black (C)	1333-86-4	0.99865727
	595.8	Fused Silica (SiO2)	60676-86-0	66.47364888
Wire Bond - Al	4.63	Aluminum (Al)	7429-90-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF